Final Product Change Notification | 201907008F01

Issue Date: 04-Aug-2019
Effective Date: 01-Nov-2019

QUALITY

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Change Category

[ ] Wafer Fab Process	[ ] Assembly Process	[ ] Product Marking	[ ] Test Location	[ ] Design
[ ] Wafer Fab Materials	[ ] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[X] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[ ] Electrical spec./Test coverage
[ ] Firmware	[X] Other - Die thickness and package substrate trace spacing modification			

SPC5777C/B/E Die Thickness Increase to 280um, Substrate Trace Spacing Modification and NXP-ATKL Assembly Site Expansion

Description of Change

NXP Semiconductors announces the following changes for the SPC5777C/ B/ E, Mask Set N45H products associated with this notification:

1. Die thickness increase from the current 179um to 280um.
2. Package substrate trace spacing modification between EXTAL and ETPUB31 will be increased.
3. Assembly site expansion from the current NXP-ATTJ, Tianjin, China assembly facility to the NXP-ATKL, Kuala Lumpur, Malaysia assembly facility.

For more information about the substrate trace spacing modification, please refer to the "Communication Package" file attached.

For the assembly site expansion, there is no change to the package bill of material (BOM) between the two assembly sites.

The above changes coincides with DeQuMa ID: SEM-PW-03, SEM-PA-09 and SEM-PA-18.

Reason for Change

Die thickness increase is to improve product quality, reliability and C55 product family standardization.
Substrate trace spacing modification is to improve device oscillator clock stability.
Site expansion qualification is required for manufacturing flexibility and customer supply assurance.

Identification of Affected Products

There is no change to the product part number marking.
The assembly site, among other information, is reflected in the package trace code.
Please refer to the marking explanation in the "Communication Package" file attached.

Product Availability

Sample Information

Samples are available upon request
Sample part numbers information is available in the "Communication Package" file attached.

Production

Planned first shipment 20-Dec-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products

Existing inventory for substrate will be shipped until depleted.
For Assembly site expansion, no depletion of inventory required.

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 03-Sep-2019.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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Affected Part Numbers	**Affected 12NC**
SPC5777CCK3MME3	935315842557
SPC5777CK3MMO3	935318909557
SPC5777CK3MME3	935320923557
SPC5775BDK3MME2	935371593557
SPC5777CDK3MMO3	935350951557
SPC5777CDK3MME4	935368231557
SPC5777CDK3MMO4	935368233557
SPC5775EDK3MME3	935370091557
SPC5777CDK3MME3	935350948557